

SnPb40-1105

Lead Solder Bar

SnPb40-1105 lead solder bar is made of high-purity tin ingots as main raw material, combined with high grade lead through a special process, using the most advanced professional lead solder equipment and excellent technology. It has reasonable alloy ratio and excellent welding performance.

FEATURES

- High purity, low metal impurity & content of oxide.
- The molten tin is smooth, flat, low viscosity and has excellent mobility.
- Unique high oxidation resistance, very small amount of tin slag
- Low surface tension, high wetting ability.
- Stable and reliable welding quality: excellent solderability, shiny and chubby solder joint.

APPLICATION

SnPb40-1105 is widely applied to communication devices, instrument equipment, automotive equipment, audio devices, household electrical, electronic appliances, manual and automatic soldering of other high reliable electronic products and special welding and painting, plating and other robotic welding.

TYPICAL PROPERTIES

Items	Technical Parameters	Standards
Part Number	SnPb40-1105	
Content of Key Alloy	Sn60 Pb40	
Appearance	Silvery white, trapezoidal cross-section strip casting alloys	Visual Inspection
Melting Point (°C)	183-190	
Density (g/cm ³)	8.5	
Shelf Life	2 years	From MGF date
Package	20kg/box, 1kg/bar	

ALLOY COMPOSITION

No.	Item	CAS. No.	Content(%)
Content of Key Alloy			
1	Tin (Sn)	7440-31-5	58.5-61.0
2	Lead (Pb)	7439-92-1	Surplus Quantity
Impurity Limit			
3	Aluminum (Al)	7429-90-5	≤0.005
	Iron (Fe)	7439-89-6	≤0.02
4	Bismuth (Bi)	7440-69-9	≤0.08
5	Zincum (Zn)	7440-66-6	≤0.002
6	Sulfur (S)	7704-34-9	≤0.020
7	Cadmium (Cd)	7440-43-9	≤0.005
8	Indium (In)	7440-74-6	≤0.10
9	Arsenic (As)	7440-38-2	≤0.03
10	Copper (Cu)	7440-50-8	≤0.05
11	Stibium (Sb)	7440-36-0	≤0.3
12	Impurity sum in addition to Sb, Bi, Cu		≤0.08

DIRECTION OF USE

- After using for a period of time, the composition of alloys will be changed, which will lead to decline the mechanical and welding performance, so the composition of solder alloys should be adjusted regularly by using pure tin. (Advice: every 10-15 days)
- Set soldering temperature according to the actual need. Recommended soldering temperature is about 230±10°C (Furnace inside practical testing temperature).

The data contained in this bulletin is provided only as a guide for evaluation/consideration. These material characteristics are typical properties that are based on a limited number of samples tested in the laboratory. We cannot assume responsibility for results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any product or method. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide.